

# NPN Transistor Bare Die - TIP31C

Rev 1.1 10/01/24

#### Bipolar Medium Power Transistor in bare die form

Complement to PNP TIP32C

#### Features:

- Collector current up to 3A
- High switching speed
- Improved h<sub>FE</sub> linearity
- Solderable back metal
- High Reliability tested grades for Military + Space

## Ordering Information:

The following part suffixes apply:

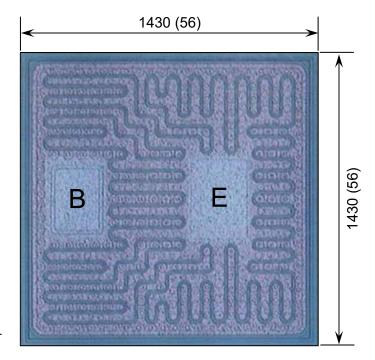
- No suffix Commercial grade die
- "H" Hi-rel grade die + MIL-STD-38534 Class H LAT
- "K" Hi-rel grade die + MIL-STD-38534 Class K LAT.

LAT = Lot acceptance Test.

For information on Hi-Rel LAT flows please see below.

www.siliconsupplies.com\bare-die-lot-qualification

## Die Dimensions in µm (mils)



**DIE BACK = COLLECTOR** 

#### **Supply Formats:**

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape Specific request
- Unsawn Wafer Specific request
- With additional electrical selection Specific request
- Sawn as pairs or adjacent pair pick Specific request

#### **Mechanical Specification**

1430 x 1430	μm	
56.30 x 56.30	mils	
310 x 430	µm	
12.20 x 16.93	mils	
310 x 430	µm	
12.20 x 16.93	mils	
230 (±25)	µm	
9.06 (±1)	mils	
Al		
Ti/Ni/Ag		
	56.30 x 56.30 310 x 430 12.20 x 16.93 310 x 430 12.20 x 16.93 230 (±25) 9.06 (±1) Al	





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### Absolute Maximum Ratings T<sub>A</sub> = 25°C unless otherwise stated

PARAMETER	SYMBOL	VALUE	UNIT
Collector-Base Voltage	V <sub>CBO</sub>	100	V
Collector-Emitter Voltage	V <sub>CEO</sub>	100	V
Emitter-Base Voltage	V <sub>EBO</sub>	5	V
Collector Current - Continuous	I <sub>C</sub>	3	A
Collector Current – Peak (t <sub>P</sub> < 5ms)	I <sub>CM</sub>	5	,,
Base Current	I <sub>B</sub>	1	A
Junction Temperature	TJ	150	°C
Storage Temperature	T <sub>stg</sub>	-55 to 150	°C

#### Electrical Characteristics T<sub>A</sub> = 25°C unless otherwise stated

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT			
OFF CHARACTERISTICS									
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	I <sub>E</sub> = 0	100	-	-	V			
Collector-Emitter Sustaining Voltage <sup>1</sup>	V <sub>CEO(SUS)</sub>	I <sub>B</sub> = 0, I <sub>C</sub> = 30mA	100	-	-	V			
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	I <sub>C</sub> = 0	5	-	-	V			
Collector Cut-off Current	I <sub>CEO</sub>	V <sub>CE</sub> = 60V, I <sub>B</sub> = 0	-	-	0.3	mA			
Emitter Cut-off Current	I <sub>EBO</sub>	V <sub>EB</sub> = 5V, I <sub>C</sub> = 0	-	-	1	mA			
Collector Cut-off Current	I <sub>CES</sub>	V <sub>CE</sub> = 100V, V <sub>EB</sub> = 0	-	-	0.2	mA			
ON CHARACTERISTICS									
Forward-Current Transfer Ratio <sup>1</sup>	h <sub>FE</sub>	I <sub>C</sub> = 1A, V <sub>CE</sub> = 4V	25	-	-	-			
	I I I E	$I_C = 3.0A, V_{CE} = 4V$	10	-	50	-			
Collector-Emitter Saturation Voltage <sup>1</sup>	V <sub>CE(sat)</sub>	I <sub>C</sub> = 3A, I <sub>B</sub> = 375mA	-	-	1.2	V			
Base-Emitter Saturation Voltage <sup>1</sup>	V <sub>BE(on)</sub>	$I_{C} = 3A, V_{CE} = 4V$	-	-	1.8	V			
SMALL SIGNAL CHARACTERISTICS <sup>2</sup>									
Transition Frequency <sup>3</sup>	f <sub>T</sub>	$V_{CE}$ = 10V, $I_C$ = 500mA, $f_{TEST}$ = 1MHz	3	-	-	MHz			
Small Signal Current Gain	h <sub>fe</sub>	V <sub>CE</sub> = 10V, I <sub>C</sub> = 500mA, f = 1kHz	20	-	-	-			

<sup>1.</sup> Pulsed duration = 300 ms, duty cycle ≥1.5%

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<sup>2.</sup> Not production testing in die form, characterized by chip design and package verification

<sup>3.</sup>  $f_T = |h_{fe}| \circ f_{TEST}$